

WEST

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File: DWPI

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TITLE: Grid array assembly method for packaging of integrated circuits - using tested single unit PCB's attached to carrier strip in automoulding of encapsulated integrated circuits to form ball grid arrays

ABTX:

Acceptable boards are attached in aligned apertures extending in a series longitudinally along an elongated carrier strip (31). An integrated circuit die (41) is mounted on the first surface of each PCB and its conductive pads are wire bonded (55) to the bonding pads on the PCB to form an assembly. Each assembly is encapsulated (61) against a portion of the first surface. The grid array assemblies, including PCB,s and encapsulated dies, are then removed from the carrier strip.

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